

Low-Voltage CMOS Quad Buffer

With 5 V-Tolerant Inputs and Outputs
(3-State, Non-Inverting)

MC74LCX125

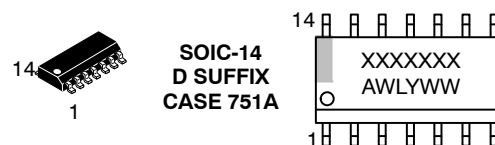
The MC74LCX125 is a high performance, non-inverting quad buffer operating from a 1.65 to 5.5 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX125 inputs to be safely driven from 5.0 V devices. The MC74LCX125 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

The Output Enable ($\overline{OEn}$) inputs, when HIGH, disable the outputs by placing them in a HIGH Z condition.

Features

- Designed for 1.65 to 5.5 V V_{CC} Operation
- 5.0 V Tolerant – Interface Capability With 5.0 V TTL Logic
- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0$ V
- LVTTTL Compatible
- LVC MOS Compatible
- 24 mA Balanced Output Sink and Source Capability @ 3.0 V
- Near Zero Static Supply Current in all Three Logic States (10 μ A)
Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 100 mA
- ESD Performance: Human Body Model >2000 V
- –Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MARKING DIAGRAMS



XXXXXX = Specific Device Code
A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

MC74LCX125

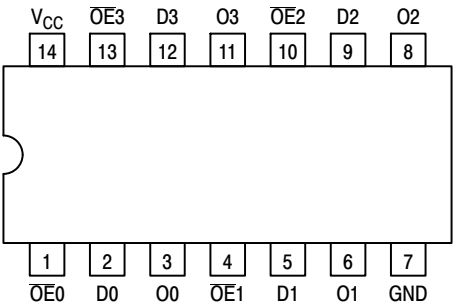


Figure 1. Pinout: 14-Lead (Top View)

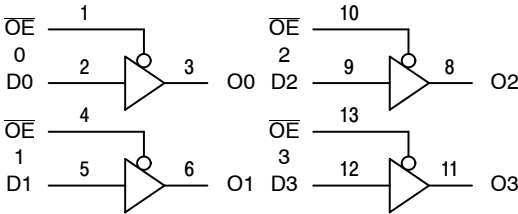


Figure 2. Logic Diagram

PIN NAMES

Pins	Function
OE _n	Output Enable Inputs
D _n	Data Inputs
O _n	3-State Outputs

TRUTH TABLE

INPUTS		OUTPUTS
OE _n	D _n	O _n
L	L	L
L	H	H
H	X	Z

H = High Voltage Level
L = Low Voltage Level
Z = High Impedance State
X = High or Low Voltage Level and Transitions Are Acceptable; for I_{CC} reasons, DO NOT FLOAT Inputs

MC74LCX125

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	-0.5 to +6.5	V
V_I	DC Input Voltage (Note 1)	-0.5 to +6.5	V
V_O	DC Output Voltage (Note 1) Active-Mode (High or Low State) Tri-State Mode Power-Down Mode ($V_{CC} = 0$ V)	-0.5 to $V_{CC} + 0.5$ -0.5 to +6.5 -0.5 to +6.5	V
I_{IK}	DC Input Diode Current $V_I < GND$	-50	mA
I_{OK}	DC Output Diode Current $V_O < GND$	-50	mA
I_O	DC Output Source/Sink Current	± 50	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin	± 100	mA
T_{STG}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 secs	260	°C
T_J	Junction Temperature Under Bias	+150	°C
θ_{JA}	Thermal Resistance (Note 1) SOIC-14 QFN14 TSSOP-14	116 130 150	°C/W
P_D	Power Dissipation in Still Air at 125°C SOIC-14 QFN14 TSSOP-14	1077 962 833	mW
MSL	Moisture Sensitivity	Level 1	-
F_R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3) Human Body Model Charged Device Model	2000 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.
2. Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
3. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage Operating Data Retention Only	1.65 1.5	3.3 3.3	5.5 5.5	V
V_I	Digital Input Voltage	0	-	5.5	V
V_O	Output Voltage Active Mode (High or Low State) Tri-State Mode Power Down Mode ($V_{CC} = 0$ V)	0 0 0	- - -	V_{CC} 5.5 5.5	V
T_A	Operating Free-Air Temperature	-40	-	+125	°C
t_r, t_f	Input Rise or Fall Rate $V_{CC} = 1.65$ V to 1.95 V $V_{CC} = 2.3$ V to 2.7 V V_I from 0.8 V to 2.0 V, $V_{CC} = 3.0$ V $V_{CC} = 4.5$ V to 5.5 V	0 0 0 0	- - - -	20 20 10 5	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

MC74LCX125

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40 °C to +85 °C		T _A = -40 °C to +125 °C		Unit
				Min	Max	Min	Max	
V _{IH}	HIGH Level Input Voltage		1.65 – 1.95	0.65 x V _{CC}	–	0.65 x V _{CC}	–	V
			2.3 – 2.7	1.7	–	1.7	–	
			3.0 – 3.6	2.0	–	2.0	–	
			4.5 – 5.5	0.70 x V _{CC}	–	0.70 x V _{CC}	–	
V _{IL}	LOW Level Input Voltage		1.65 – 1.95	–	0.35 x V _{CC}	–	0.35 x V _{CC}	V
			2.3 – 2.7	–	0.7	–	0.7	
			3.0 – 3.6	–	0.8	–	0.8	
			4.5 – 5.5	–	0.30 x V _{CC}	–	0.30 x V _{CC}	
V _{OH}	High-Level Output Voltage	V _I = V _{IH} or V _{IL} I _{OH} = -100 µA I _{OH} = -4 mA I _{OH} = -8 mA I _{OH} = -12 mA I _{OH} = -16 mA I _{OH} = -24 mA I _{OH} = -32 mA	1.65 to 5.5	V _{CC} - 0.1	–	V _{CC} - 0.1	–	V
			1.65	1.29	–	1.29	–	
			2.3	1.8	–	1.8	–	
			2.7	2.2	–	2.2	–	
			3.0	2.4	–	2.4	–	
			3.0	2.2	–	2.2	–	
			4.5	3.7	–	3.7	–	
V _{OL}	Low-Level Output Voltage	V _I = V _{IH} or V _{IL} I _{OL} = 100 µA I _{OL} = 4 mA I _{OL} = 8 mA I _{OL} = 12 mA I _{OL} = 16 mA I _{OL} = 24 mA I _{OL} = 32 mA	1.65 to 5.5	–	0.1	–	0.1	V
			1.65	–	0.24	–	0.24	
			2.3	–	0.3	–	0.3	
			2.7	–	0.4	–	0.4	
			3.0	–	0.4	–	0.4	
			3.0	–	0.55	–	0.55	
			4.5	–	0.6	–	0.6	
I _{OZ}	3-State Output Leakage Current	V _I = V _{IH} or V _{IL} , V _O = 0 to 5.5 V	3.6	–	±5.0	–	±5.0	µA
I _I	Input Leakage Current	V _I = 0 to 5.5 V	3.6	–	±5.0	–	±5.0	µA
I _{OFF}	Power Off Leakage Current	V _I = 5.5 V or V _O = 5.5 V	0	–	10	–	10	µA
I _{CC}	Quiescent Supply Current	V _I = 5.5 V or GND	3.6	–	10	–	10	µA
ΔI _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} - 0.6 V	2.3 to 3.6	–	500	–	500	µA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Condition	V _{CC} (V)	T _A = -40 °C to +85 °C		T _A = -40 °C to +125 °C		Unit
				Min	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, Input to Output	See Figures 3 and 4	1.65 to 1.95	–	11.0	–	11.0	ns
			2.3 to 2.7	–	7.2	–	7.2	
			2.7	–	6.5	–	6.5	
			3.0 to 3.6	–	6.0	–	6.0	
			4.5 to 5.5	–	4.7	–	4.7	

MC74LCX125

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Condition	V _{CC} (V)	T _A = -40 °C to +85 °C		T _A = -40 °C to +125 °C		Unit
				Min	Max	Min	Max	
t _{pZH} , t _{pZL}	Output Enable Time	See Figures 3 and 4	1.65 to 1.95	–	11.3	–	11.3	ns
			2.3 to 2.7	–	9.1	–	9.1	
			2.7	–	8.0	–	8.0	
			3.0 to 3.6	–	7.0	–	7.0	
			4.5 to 5.5	–	6.0	–	6.0	
t _{pHZ} , t _{pLZ}	Output Disable Time	See Figures 3 and 4	1.65 to 1.95	–	9.0	–	9.0	ns
			2.3 to 2.7	–	7.2	–	7.2	
			2.7	–	7.0	–	7.0	
			3.0 to 3.6	–	6.0	–	6.0	
			4.5 to 5.5	–	5.0	–	5.0	
t _{OSHL} , t _{OSLH}	Output to Output Skew		1.65 to 1.95	–	–	–	–	ns
			2.3 to 2.7	–	–	–	–	
			2.7	–	–	–	–	
			3.0 to 3.6	–	1.0	–	1.0	
			4.5 to 5.5	–	–	–	–	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

DYNAMIC SWITCHING CHARACTERISTICS

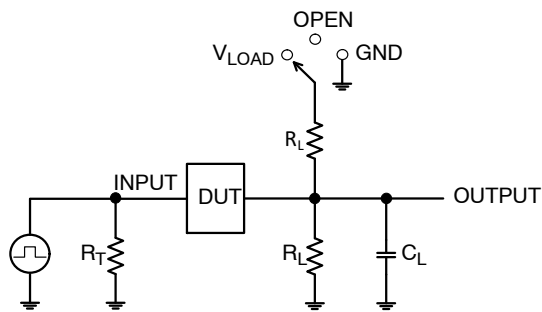
Symbol	Characteristic	Condition	T _A = +25 °C			Unit
			Min	Typ	Max	
V _{OLP}	Dynamic LOW Peak Voltage (Note 5)	V _{CC} = 3.3 V, C _L = 50 pF, V _{IH} = 3.3 V, V _{IL} = 0 V V _{CC} = 2.5 V, C _L = 30 pF, V _{IH} = 2.5 V, V _{IL} = 0 V		0.8 0.6		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 5)	V _{CC} = 3.3 V, C _L = 50 pF, V _{IH} = 3.3 V, V _{IL} = 0 V V _{CC} = 2.5 V, C _L = 30 pF, V _{IH} = 2.5 V, V _{IL} = 0 V		–0.8 –0.6		V

5. Number of outputs defined as “n”. Measured with “n–1” outputs switching from HIGH–to–LOW or LOW–to–HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typ	Unit
C _{IN}	Input Capacitance	V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	7	pF
C _{OUT}	Output Capacitance	V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	25	pF

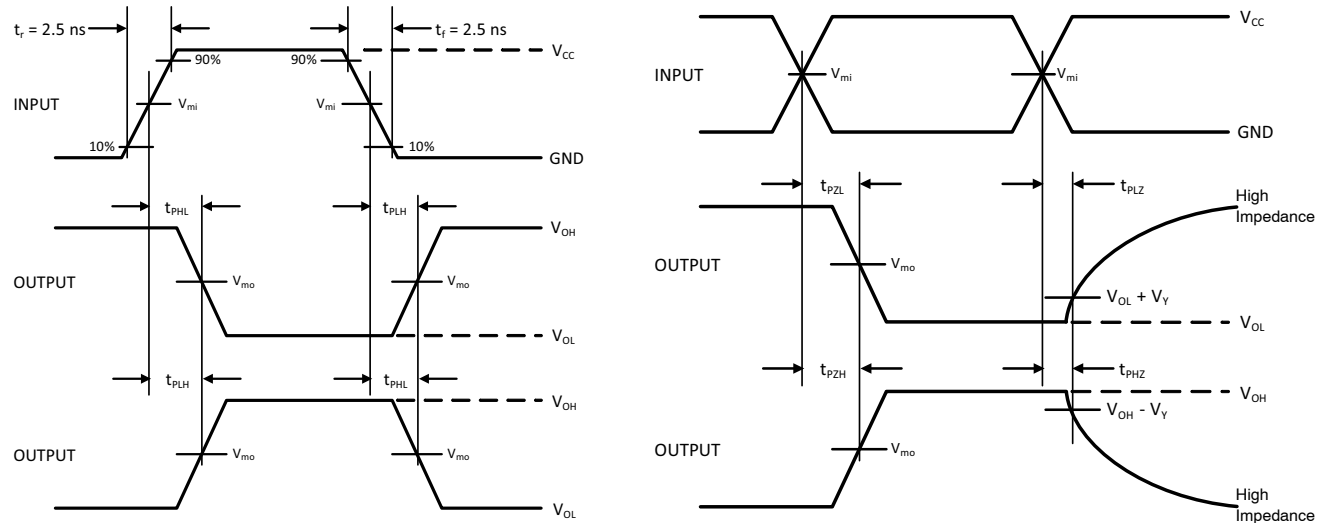
MC74LCX125



C_L includes probe and jig capacitance
R_T is Z_{OUT} of pulse generator (typically 50 Ω)
f = 1 MHz

Test	Switch Position
t _{PLH} / t _{PHL}	Open
t _{PLZ} / t _{PZL}	V _{LOAD}
t _{PHZ} / t _{PZH}	GND

Figure 3. Test Circuit



V _{CC} , V	R _L , Ω	C _L , pF	V _{LOAD}	V _m , V	V _y , V
1.65 to 1.95	500	30	2 x V _{CC}	V _{CC} /2	0.15
2.3 to 2.7	500	30	2 x V _{CC}	V _{CC} /2	0.15
2.7	500	50	6 V	1.5	0.3
3.0 to 3.6	500	50	6 V	1.5	0.3
4.5 to 5.5	500	50	2 x V _{CC}	V _{CC} /2	0.3

Figure 4. Switching Waveforms

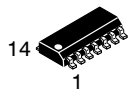
MC74LCX125

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
MC74LCX125DG	LCX125G	SOIC-14	55 Units / Rail
MC74LCX125DR2G	LCX125G	SOIC-14	2500 / Tape & Reel
MC74LCX125DTG	LCX 125	TSSOP-14	96 Units / Rail
MC74LCX125DTR2G	LCX 125	TSSOP-14	2500 / Tape & Reel
MC74LCX125DTR2G-Q*	LCX 125	TSSOP-14	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

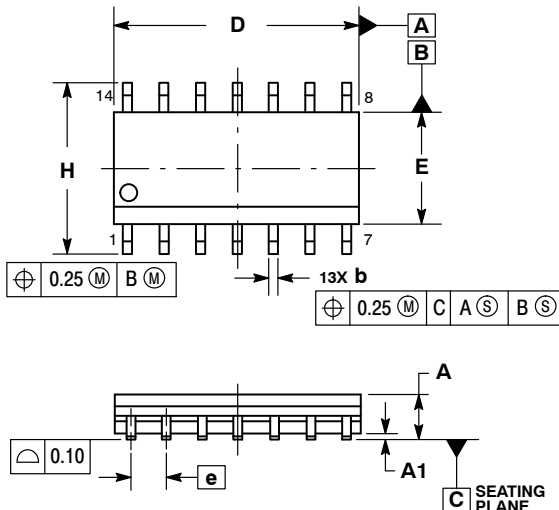
*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.



SCALE 1:1

SOIC-14 NB
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

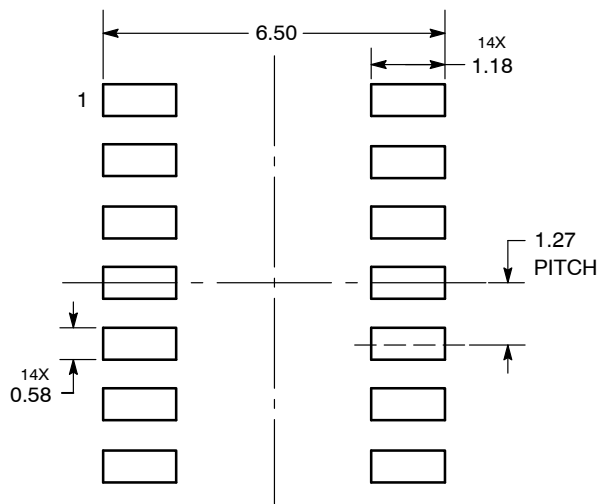


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

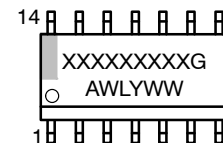
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. COMMON CATHODE
12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

STYLE 8:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

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